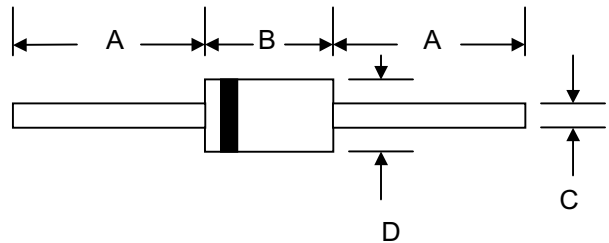


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**Features**

- Schottky Barrier Chip
- Guard Ring Die Construction for Transient Protection
- High Current Capability
- Low Power Loss, High Efficiency
- High Surge Current Capability
- For Use in Low Voltage, High Frequency Inverters, Free Wheeling, and Polarity Protection Applications



**Mechanical Data**

- Case: Molded Plastic
- Terminals: Plated Leads Solderable per MIL-STD-202, Method 208
- Polarity: Cathode Band
- Weight: 1.2 grams (approx.)
- Mounting Position: Any
- Marking: Type Number

DO-201AD				
Dim	Min	Max	Min	Max
A	25.40	—	1.000	—
B	8.50	9.50	0.334	0.374
C	1.20	1.30	0.047	0.051
D	5.00	5.60	0.197	0.220
	In mm		In inch	

**Maximum Ratings and Electrical Characteristics** @T<sub>A</sub>=25°C unless otherwise specified

Single Phase, half wave, 60Hz, resistive or inductive load.  
For capacitive load, derate current by 20%.

Characteristic	Symbol	SB320	SB330	SB340	SB350	SB360	Unit	
Peak Repetitive Reverse Voltage	V <sub>RRM</sub>							
Working Peak Reverse Voltage	V <sub>RWM</sub>	20	30	40	50	60	V	
DC Blocking Voltage	V <sub>R</sub>							
RMS Reverse Voltage	V <sub>R(RMS)</sub>	14	21	28	35	42	V	
Average Rectified Output Current (Note 1) @T <sub>L</sub> = 95°C	I <sub>O</sub>	3.0						A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I <sub>FSM</sub>	80						A
Forward Voltage @I <sub>F</sub> = 3.0A	V <sub>FM</sub>	0.50			0.74		V	
Peak Reverse Current @T <sub>A</sub> = 25°C At Rated DC Blocking Voltage @T <sub>A</sub> = 100°C	I <sub>RM</sub>	0.5 20					mA	
Typical Junction Capacitance (Note 2)	C <sub>j</sub>	250					pF	
Typical Thermal Resistance Junction to Ambient	R <sub>θJA</sub>	20					K/W	
Operating and Storage Temperature Range	T <sub>j</sub> , T <sub>STG</sub>	-65 to +150					°C	

Note: 1. Valid provided that leads are kept at ambient temperature at a distance of 9.5mm from the case.  
2. Measured at 1.0 MHz and applied reverse voltage of 4.0V D.C.

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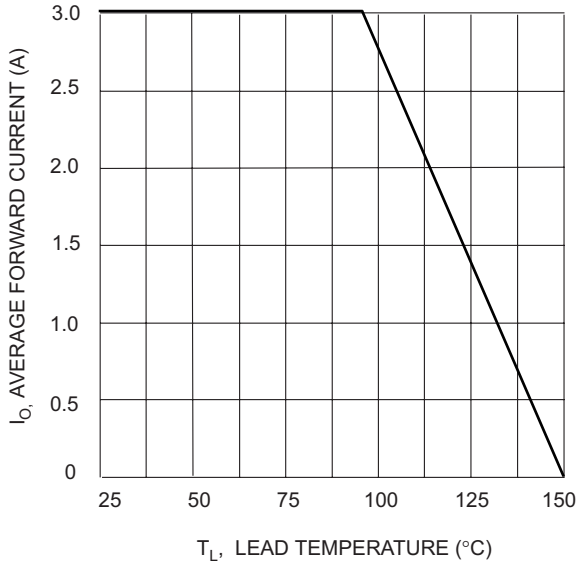


Fig. 1 Forward Current Derating Curve

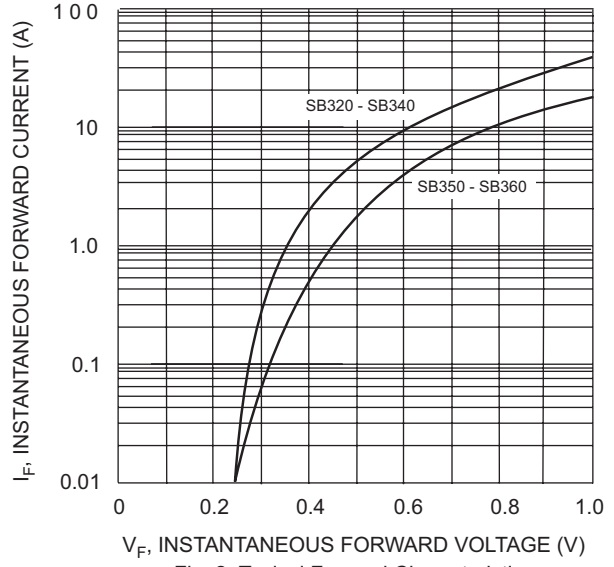


Fig. 2 Typical Forward Characteristics

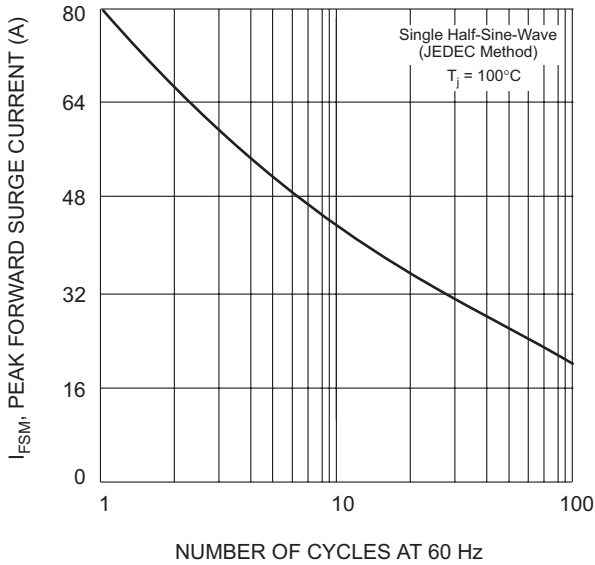


Fig. 3 Max Non-Repetitive Peak Fwd Surge Current

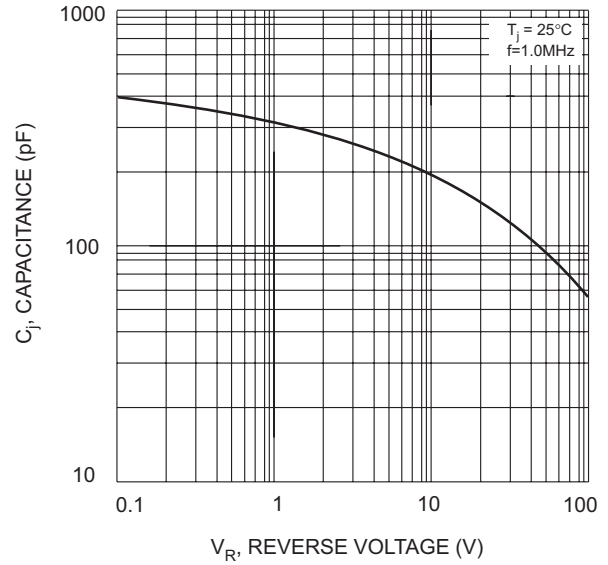


Fig. 4 Typical Junction Capacitance

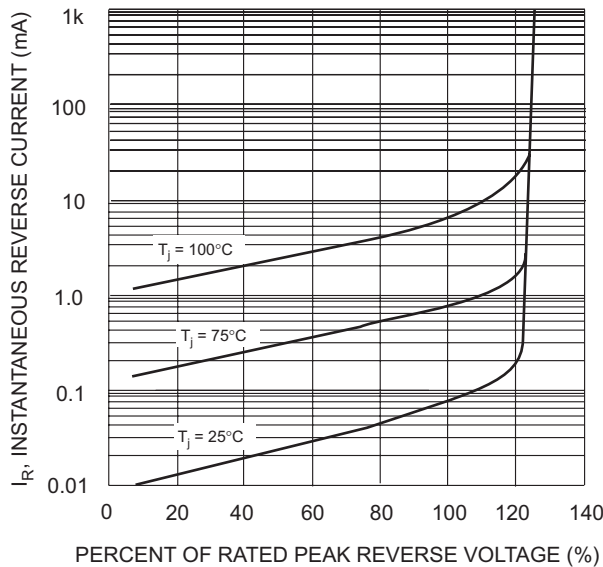


Fig. 5 Typical Reverse Characteristics

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